

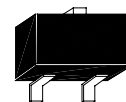


HBC807

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HBC807 is designed for switching and AF amplifier amplification suitable for driver stages and low power output stages.



SOT-23

Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 to +150 °C
Junction Temperature..... +150 °C
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 225 mW
- Maximum Voltages and Currents (Ta=25°C)
VCES Collector to Base Voltage -50 V
VCEO Collector to Emitter Voltage..... -45 V
VEBO Emitter to Base Voltage -5 V
IC Collector Current..... -800 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	-45	-	-	V	IC=-10mA
BVCES	-50	-	-	V	IC=-100uA
BVEBO	-5	-	-	V	IE=-100uA
ICES	-	-	-100	nA	VCE=-25V
IEBO	-	-	-100	nA	VEB=-4V
*VCE(sat)	-	-	-700	mV	IC=-500mA, IB=-50mA
VBE(on)	-	-	-1.2	V	VCE=-1V, IC=-300mA
*hFE	100	-	630		VCE=-1V, IC=-100mA
fT	-	100	-	MHz	VCE=-5V, IC=-10mA, f=100MHz
Cob	-	-	12	pF	VCB=-10V, f=1MHz, IE=0

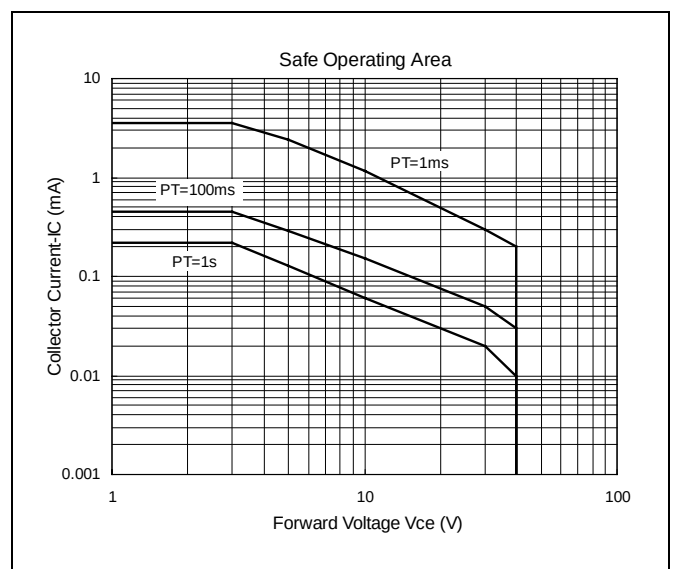
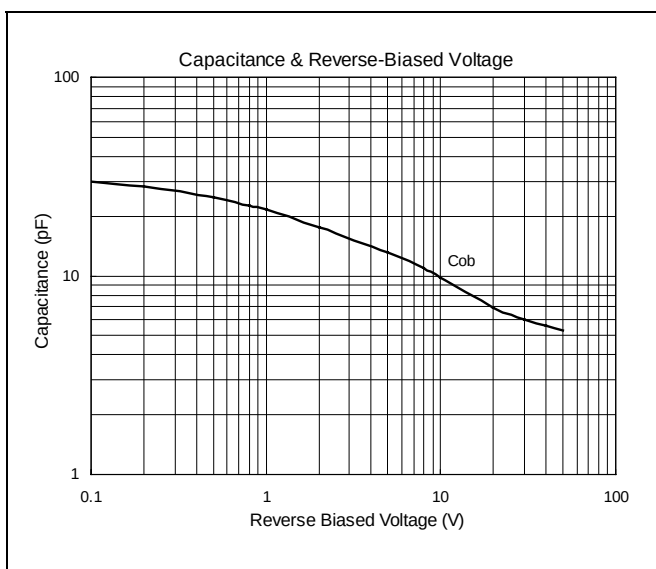
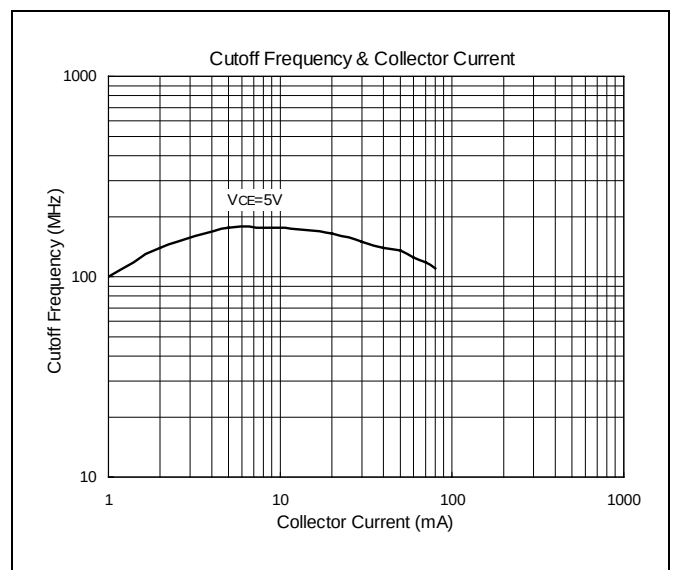
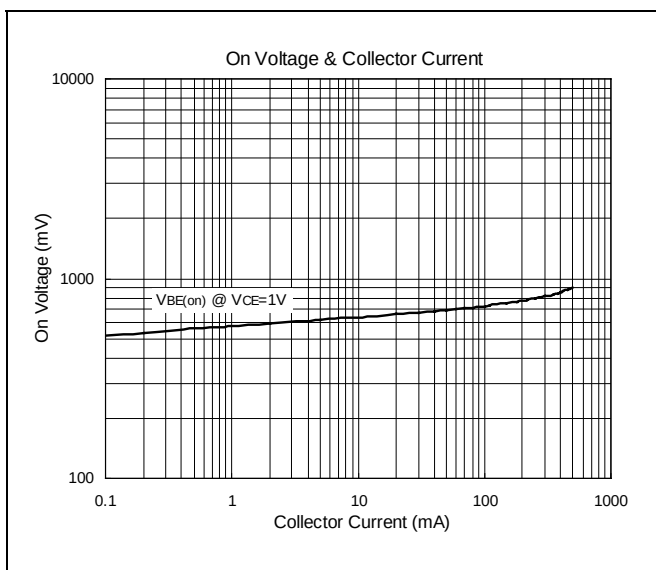
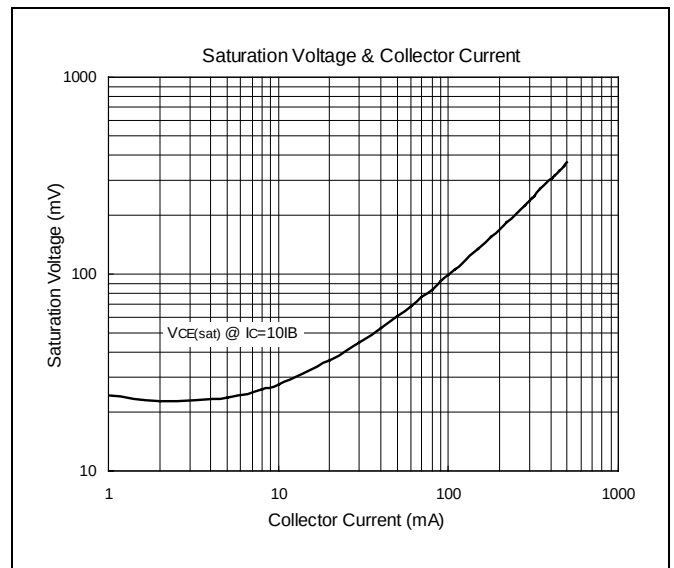
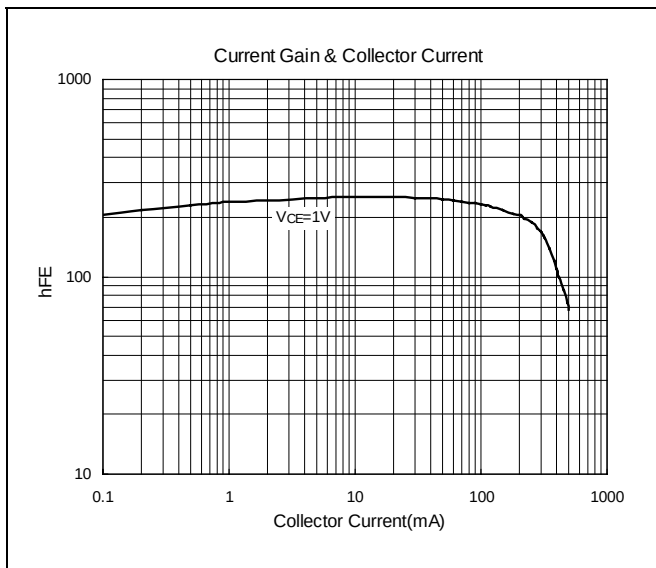
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE

Rank	9FA(16)	9FB(25)	9FC(40)
hFE	100-250	160-400	250-630

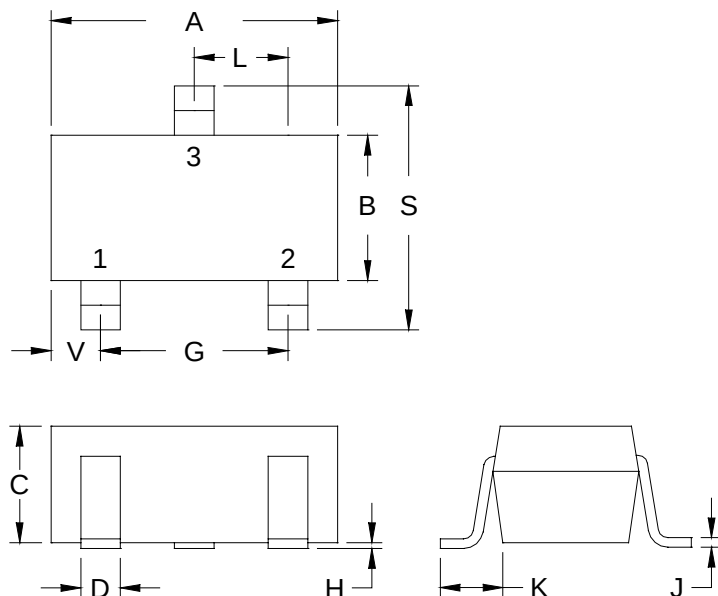


Characteristics Curve

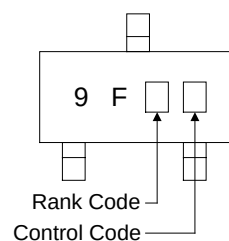




SOT-23 Dimension



Marking:



3-Lead SOT-23 Plastic
Surface Mounted Package
HSMC Package Code: N

Style: Pin 1.Base 2.Emitter 3.Collector

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension: millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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